

ABSTRACT

SUBSTRATE PROCESSING APPARATUS AND PIPE CLEANING METHOD FOR SUBSTRATE PROCESSING APPARATUS

5 The present invention relates to a substrate processing apparatus for processing a
substrate, such as a wafer, while supplying a cleaning liquid (e.g. pure water and a liquid
chemical) to the substrate, and also relates to a pipe cleaning method for the substrate
processing apparatus. The substrate processing apparatus includes: a first cleaning lane
including first cleaning units (52), (54) each for cleaning a substrate while supplying pure
10 water to the substrate; a second cleaning lane including second cleaning units (60), (62)
each for cleaning a substrate while supplying pure water to the substrate; a first
pure-water supply pipe (120) for supplying the pure water to the first cleaning lane; and a
second pure-water supply pipe (180) for supplying the pure water to the second cleaning
lane.

15 Figure 8